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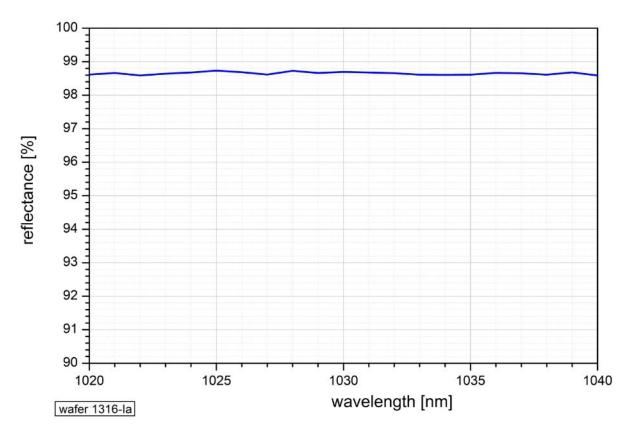


SAM™ Data Sheet SAM-1030-1-5ps-100-x, λ = 1030 nm

| | Minimum | Typical Value | Maximum |
|------------------------------------|--|------------------------|--------------------|
| Operational wavelength λ | | 1030 nm | |
| High reflection band | 1020 nm | - | 1040 nm |
| Absorbance A | 0.7 % | 1 % | 1.5 % |
| Modulation depth Δ | 0.4 % | 0.6 % | - |
| Non-saturable loss A _{ns} | - | 0.4 % | 0.8 % |
| Saturation fluence Φ_{sat} | 50 μJ/cm² | 100 µJ/cm² | 150 μJ/cm² |
| Relaxation time constant τ | 3 ps | 5 ps | 8 ps |
| Damage threshold Φ | | 800 µJ/cm ² | |
| Absorber Peak Temperature | | | 150°C ¹ |
| Chip thickness | 425 µm | 450 µm | 475 μm |
| Protection | SAM is protected with a dielectric front layer | | |

Please make sure that this temperature is not exceeded in pulsed operation shortly after the optical pulse.

Low intensity spectral reflectance



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| Mounting Options | | | |
|--|---|--|--|
| SAM-1030-20-15ps-50-x | Description | | |
| x = 4.0-0 | Single chip, unmounted, chip size 4.0mm x 4.0mm | | |
| x = 1.0b-0 | Batch of 4 unmounted chips, chip size 1.0mm x 1.0mm | | |
| x = 1.3b-0 | Batch of 4 unmounted chips, chip size 1.3mm x 1.3mm | | |
| | | | |
| x = 4.0-12.7g-c / 4.0-12.7g-e | chip size 4.0mm x 4.0mm, glued on a gold plated Cu-cylinder with 12.7 mm diameter | | |
| x = 4.0-25.0g-c / 4.0-25.0g-e | chip size 4.0mm x 4.0mm, glued on a gold plated Cu-cylinder with 25.0 mm diameter | | |
| x = 4.0-25.4g-c / 4.0-25.4g-e | chip size 4.0mm x 4.0mm, glued on a gold plated Cu-cylinder with 25.4 mm diameter | | |
| x = 4.0-12.7s-c / 4.0-12.7s-e | chip size 4.0mm x 4.0mm, soldered on a gold plated Cu-cylinder with 12.7 mm diameter | | |
| x = 4.0-25.0s-c / 4.0-25.0s-e | chip size 4.0mm x 4.0mm, soldered on a gold plated Cu-cylinder with 25.0 mm diameter | | |
| x = 4.0-25.4s-c / 4.0-25.4s-e | chip size 4.0mm x 4.0mm, soldered on a gold plated Cu-cylinder with 25.4 mm diameter | | |
| x = 4.0-25.0w-c / 4.0-25.0w-e | chip size 4.0mm x 4.0mm, soldered on a water cooled copper heat sink with 25.0 mm diameter | | |
| x = 4.0-25.4h-c / 4.0-25.4h-e | chip size 4.0mm x 4.0mm, thin film soldered on a water cooled copper heat sink with 25.0 mm diameter for high power application | | |
| -c Center mounting | -e Edge mounting | | |
| x = FC/(A)PC-SMF | mounted on a 1 m long single mode fiber | | |
| | FC/PC connector: x = FC/PC-SMF FC/APC connector: x = FC/APC-SMF | | |
| | available fiber types: HI 980, HI 1060 | | |
| x = FC/(A)PC-PMF | mounted on a 1 m long polarization maintaining fiber | | |
| | FC/PC connector: x = FC/PC-PMF FC/APC connector: x = FC/APC-PMF | | |
| | available fiber types: SM98-PS-U25D | | |
| Other chip dimensions are also possible, please ask. | | | |